|  |  |  |
| --- | --- | --- |
| *General information* | |  |
| Company | … | *COMPANY*  *LOGO* |
| Company Classification | Choose Classification |
| Company type | Choose Type |
| Areas of interest (in IPCEI ME/CT) |  |
| Position in Value Chain |  |
| Country | Romania |
| Participation | Direct Partner |
| Project title |  |
| Main work-stream contribution | THINK  ACT  SENSE  COMMUNICATE |
| ain work packages | WP 1 “Tools and technologies”  WP 2 “Semiconductor technologies, innovative, smart, sustainable manufacturing”  WP 3 “Components and modules”  WP 4 “Subsystems and systems for communication technologies and further downstream industries” | |

|  |  |  |  |
| --- | --- | --- | --- |
|  | | | |
| Person of contact |  | **E-mail for contact** |  |
| Cooperation offers |  | | |
| Needed  Cooperation |  | | |
| Planned  Cooperation | *(Indirect partners to be mentioned)* | | |

|  |
| --- |
| Presentation of the company |
| *Company description* *without confidential information.* |

|  |
| --- |
| Project idea |
| *Summary and description* of the planned project within IPCEI ME/CT *without confidential information.* |

|  |  |
| --- | --- |
| Key Innovations |  |
| Addressed key objective |  |
| Addressed key challenges |  |
| Strategic Importance  *(EU objectives: Green Deal, Digital Transformation, European Footprint on Microelectronics, Resilience, Sovereignty, Digital Decade, Industry Strategy, Joint declaration).* | *Describe shortly how the project will contribute to the EU objectives* |